

UNISONIC TECHNOLOGIES CO., LTD

# 2N60-HD

Preliminary

# 2A, 600V N-CHANNEL POWER MOSFET

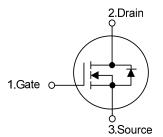
# DESCRIPTION

The UTC **2N60-HD** is a high voltage power MOSFET designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and high rugged avalanche characteristics. This power MOSFET is usually used in high speed switching applications of switching power supplies and adaptors.

### FEATURES

- \*  $R_{DS(ON)} \le 6.0 \ \Omega$  @  $V_{GS}=10V$ ,  $I_D=1.0A$
- \* Fast switching capability
- \* Avalanche energy tested
- \* Improved dv/dt capability, high ruggedness

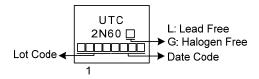
### SYMBOL

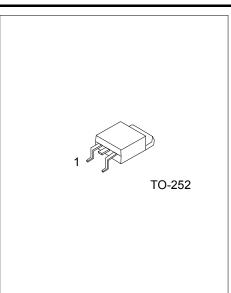


## ORDERING INFORMATION

Ordering Number		Daakaga	Pin Assignment			Deelving	
Lead Free Halogen Free		Package	1	2	3	Packing	
2N60L-TN3-R	2N60L-TN3-R 2N60G-TN3-R			D	S	Tape Reel	
Note: Pin Assignment: G: Gate D: Drain S: Source							
2N60 <u>G-TN3</u> -R							
	(1) R: Tape Reel						
	(2) TN3: TO-252						
(3) G: Halogen Free and Lead				Lead Fr	ee, L: Le	ad Free	

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### ■ ABSOLUTE MAXIMUM RATINGS (T<sub>c</sub> = 25°C, unless otherwise specified)

PARAMETER	SYMBOL	RATINGS	UNIT	
Drain-Source Voltage	V <sub>DSS</sub>	600	V	
Gate-Source Voltage	V <sub>GSS</sub>	±30	V	
Continuous Drain Current	ID	2	А	
Pulsed Drain Current (Note 2)	I <sub>DM</sub>	4	А	
Avalanche Energy Single Pulsed (Note	3) E <sub>AS</sub>	63	mJ	
Peak Diode Recovery dv/dt (Note 4)	dv/dt	3.8	V/ns	
Power Dissipation	PD	36	W	
Junction Temperature	TJ	+150	°C	
Storage Temperature	T <sub>STG</sub>	-55 ~ +150	°C	

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. L = 30mH,  $I_{AS}$  = 2.0A,  $V_{DD}$  = 60V,  $R_{G}$  = 25  $\Omega$ , Starting  $T_{J}$  = 25  $^{\circ}C$ 

4.  $I_{SD} \le 2.0A$ , di/dt  $\le 200A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J = 25^{\circ}C$ 

### THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT	
Junction to Ambient	θ <sub>JA</sub>	110	°C/W	
Junction to Case	θ <sub>JC</sub>	3.47 (Note)	°C/W	

Note: Device mounted on FR-4 substrate  $P_C$  board, 2oz copper, with 1inch square copper plate.

### ■ ELECTRICAL CHARACTERISTICS (T<sub>J</sub>=25°C, unless otherwise specified)

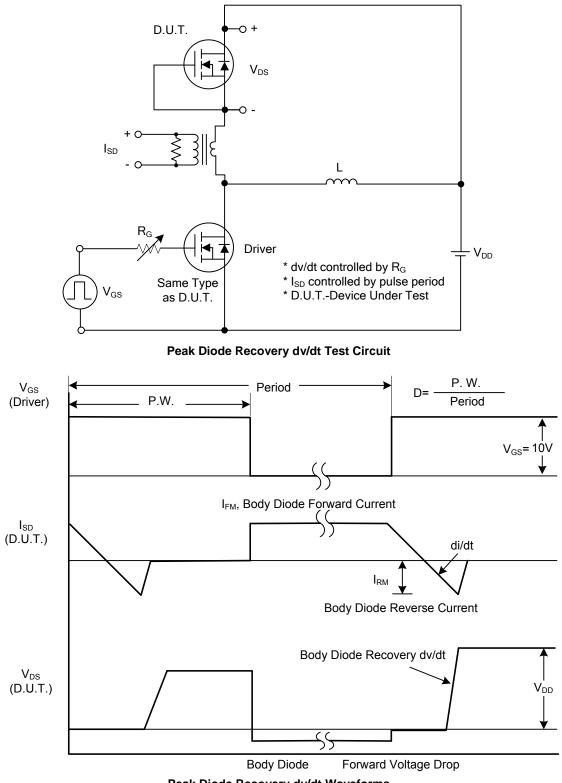
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PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250µA	600			V
Drain-Source Leakage Current		I <sub>DSS</sub>	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V			10	μA
Gate- Source Leakage Current	Forward		V <sub>GS</sub> = 30V, V <sub>DS</sub> = 0V			100	nA
	Reverse	- I <sub>GSS</sub>	$V_{GS} = -30V, V_{DS} = 0V$			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		V <sub>GS(TH)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250µA	2.0		4.0	V
Static Drain-Source On-State Resistance		R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 1.0A			6.0	Ω
DYNAMIC CHARACTERISTICS							
Input Capacitance		CISS			239.7		pF
Output Capacitance		Coss	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0 MHz		28.5		рF
Reverse Transfer Capacitance		C <sub>RSS</sub>			2.3		pF
SWITCHING CHARACTERISTIC	S						
Total Gate Charge (Note 1)		$Q_{G}$			11.2		nC
Gate-Source Charge		Q <sub>GS</sub>	$V_{DS}$ =480V, $V_{GS}$ =10V, $I_D$ =2.0A,		4.6		nC
Gate-Drain Charge		$Q_{GD}$	I <sub>D</sub> =1mA (Note 1, 2)		1.6		nC
Turn-On Delay Time (Note 1)		t <sub>D(ON)</sub>			3.8		ns
Turn-On Rise Time		t <sub>R</sub>	V <sub>DD</sub> =100V, V <sub>GS</sub> =10V, I <sub>D</sub> =2.0A,		15.7		ns
Turn-Off Delay Time		t <sub>D(OFF)</sub>	R <sub>G</sub> =25Ω (Note 1, 2)		18.2		ns
Turn-Off Fall Time		t⊢			25.7		ns
DRAIN-SOURCE DIODE CHARA	CTERISTIC	CS AND MA	XIMUM RATINGS				
Maximum Body-Diode Continuous Current		ls				2	Α
Maximum Body-Diode Pulsed Current		I <sub>SM</sub>				4	Α
Drain-Source Diode Forward Voltage		$V_{SD}$	I <sub>S</sub> =2.0A , V <sub>GS</sub> =0V			1.4	V
Body Diode Reverse Recovery Time		t <sub>rr</sub>	I <sub>S</sub> =2.0A , V <sub>GS</sub> =0V		195.7		ns
Body Diode Reverse Recovery Charge		Qrr	di/dt=100A/µs		1.8		μC
Notes: 1 Pulse Test: Pulse width		ity cycle < 2	00/				

Notes: 1. Pulse Test: Pulse width  $\leq$  300µs, Duty cycle  $\leq$  2%.

2. Essentially independent of operating temperature.

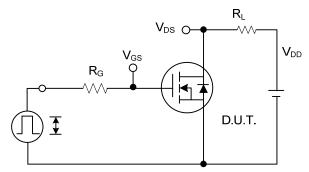
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### TEST CIRCUITS AND WAVEFORMS

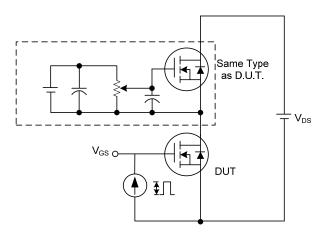


Peak Diode Recovery dv/dt Waveforms

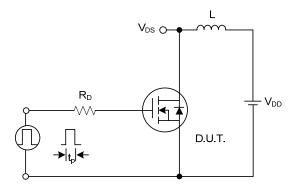
## TEST CIRCUITS AND WAVEFORMS



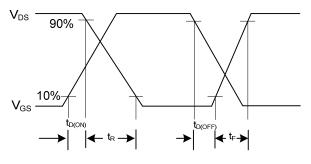
Switching Test Circuit



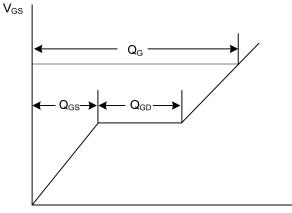
**Gate Charge Test Circuit** 



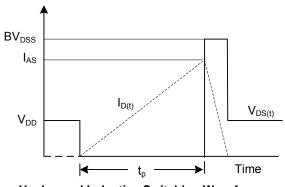
**Unclamped Inductive Switching Test Circuit** 







Charge Gate Charge Waveform



**Unclamped Inductive Switching Waveforms** 

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